

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6376904".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:33
L2	2	"20030155659"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 15:34
L3	2	"20020140107"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:23
L4	2341454	(semiconductor die chip dice ic component electronic (integrated adj circuit)) with (stack\$6 mount\$4 first second top bottom upper lower multi multiple)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:42
L5	41069	(cascad\$4 tilt\$3 lean\$3 slang\$4) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:44
L6	308234	(cascad\$4 tilt\$3 lean\$3 slang\$4 expos\$4 showing) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:31
L7	5120	(cascad\$4 tilt\$3 lean\$3 slang\$4) same (expos\$4 showing) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:31
L8	754	(conduc\$3 wire wiring) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:45

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L9	5031044	t	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:32
L10	959	(conduct\$3 wire wiring) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:32
L11	325260	(semiconductor die chip dice ic component electronic (integrated adj circuit)) with (stack\$6 mount\$4) same (first second top bottom upper lower multi multiple)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:42
L12	8374	(cascad\$4 tilt\$3 lean\$3 slang\$4) same 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:48
L13	8039	12 not 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:44
L14	2523	(conduc\$3 wire wiring) and 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:48
L15	1645	(packag\$4 structure module) and 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:50
L16	1390	(electrode contact terminal pad) and 15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:50

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L17	16586	(cascad\$4 tilt\$3 lean\$3 offset\$5 slang\$4) same 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:48
L18	16241	17 not 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:48
L19	5780	(conduc\$3 wire wiring) and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:49
L20	6449	(conduct\$3 wire wiring) and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:49
L21	5332	(electrode contact terminal pad) and 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:50
L22	3773	(packag\$4 structure module) and 21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:50
L23	2976	22 and (frame board substrate carrier pcb ((wiring printed circuit) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:52
L24	2816	(pattern\$3 redistribut\$4 position\$4) and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:54

## EAST Search History

L25	2776	(connect\$4 electric\$4 interconnect\$4) and 24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/17 16:54
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